

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.04686	10.0	0.70985
	Silver alloy	Silver (Ag)	7440-22-4	0.00937	2.0	0.14197
	Lead alloy	Lead (Pb)	7439-92-1	0.41236	88.0	6.24666
Subtotal				0.46859	100	7.09848
Die		Lead Dioxide (PbO2)	1309-60-0	0.00436	0.66	0.066
	Doped silicon	Silicon (Si)	7440-21-3	0.65577	99.34	9.934
Subtotal				0.66013	100	10
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.19248	100.0	2.9158
		Subtotal				0.19248
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.00922	0.03	0.13965
	Copper alloy	Iron (Fe)	7439-89-6	0.0338	0.11	0.51205
	Copper alloy	Copper (Cu)	7440-50-8	30.68581	99.86	464.8483
Subtotal				30.72883	100	465.5
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.32016	100.0	4.85
		Subtotal				0.32016
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	5.41039	8.0	81.96
	Filler	Silica fused	60676-86-0	54.78016	81.0	829.845
	Metal hydroxide	Metal hydroxide		0.47341	0.7	7.1715
	Carbon Black	Carbon black	1333-86-4	0.20289	0.3	3.0735
	Polymer	Epoxy resin system		6.76298	10.0	102.45
Subtotal				67.62983	100	1024.5
Total				100.00002	100	1514.86428

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